



Material Content Data Sheet



Sales Product Name		BCM 856S H6327		Issued		1. August 2018		
MA#		MA000849484						
Package		PG-SOT363-6-1		Weight*		6.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		15	
	noble metal	gold	7440-57-5	0.009	0.15		1459	
	inorganic material	silicon	7440-21-3	0.078	1.25	1.40	12464	13938
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		459	
	non noble metal	chromium	7440-47-3	0.009	0.14		1376	
	non noble metal	copper	7440-50-8	2.869	45.67	45.87	456783	458710
wire	non noble metal	copper	7440-50-8	0.010	0.17	0.17	1661	1661
encapsulation	organic material	carbon black	1333-86-4	0.030	0.48		4828	
	plastics	epoxy resin	-	0.652	10.38		103801	
	inorganic material	silicondioxide	60676-86-0	2.350	37.42	48.28	374166	482795
leadfinish	non noble metal	tin	7440-31-5	0.213	3.39	3.39	33947	33947
plating	noble metal	silver	7440-22-4	0.056	0.89	0.89	8949	8949
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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